

**80V NPN MEDIUM POWER TRANSISTOR IN TO126**

**Features**

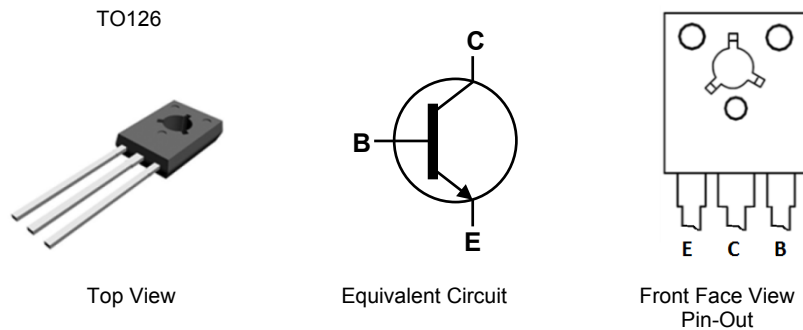
- $BV_{CEO} > 80V$
- $I_C = 1A$  Continuous Collector Current
- $I_{CM} = 2A$  Peak Pulse Current
- Low Saturation Voltage  $V_{CE(sat)} < 500mV @ 0.5A$
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

**Mechanical Data**

- Case: TO126
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin Finish; Solderable per MIL-STD-202, Method 208
- Weight: TO126: 400mg (Approximate)

**Applications**

- Medium Power Switching or Amplification Applications
- AF driver and output stages

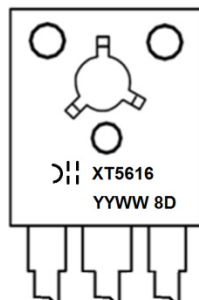


**Ordering Information** (Note 4)

Product	Package	Marking	Quantity
DXT5616U	TO126	XT5616	1,690 per box in tubes (65 per tube)

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**



XT5616 = Product type marking code  
 Date Code Format = YYWW  
 YY = Last two digits of Year (ex 14=2014)  
 WW = Week (01-53)  
 8D = Assembly and Foundry code

### Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	100	V
Collector-Emitter Voltage	$V_{CEO}$	80	V
Emitter-Base Voltage	$V_{EBO}$	5	V
Continuous Collector Current	$I_C$	1	A
Peak Pulse Collector Current	$I_{CM}$	2	
Continuous Base Current	$I_B$	100	mA
Peak Pulse Base Current	$I_{BM}$	200	

### Thermal Characteristics (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

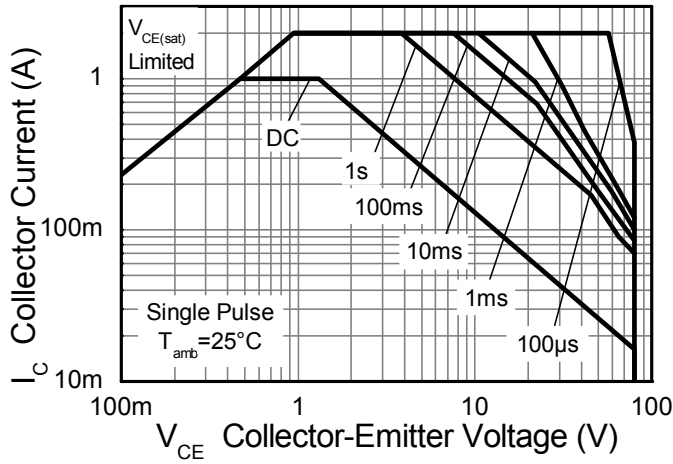
Characteristic	Symbol	Value	Unit
Power Dissipation	(Note 5)	1.3	W
	(Note 6) $T_L = +25^\circ\text{C}$	20	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	96	$^\circ\text{C/W}$
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	6.25	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	$^\circ\text{C}$

### ESD Ratings (Note 7)

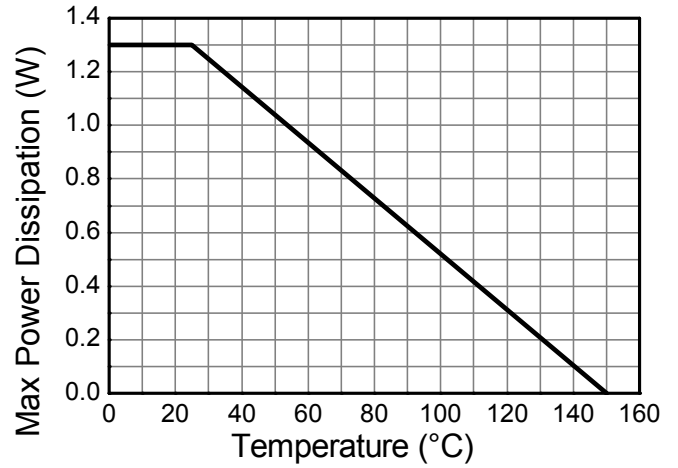
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a through-hole device mounted on minimum recommended pad layout with 10mm lead length from the bottom of package to the board that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  - Thermal resistance from junction to solder-point at the seating plane (2.5mm from the bottom of package along the collector lead).
  - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

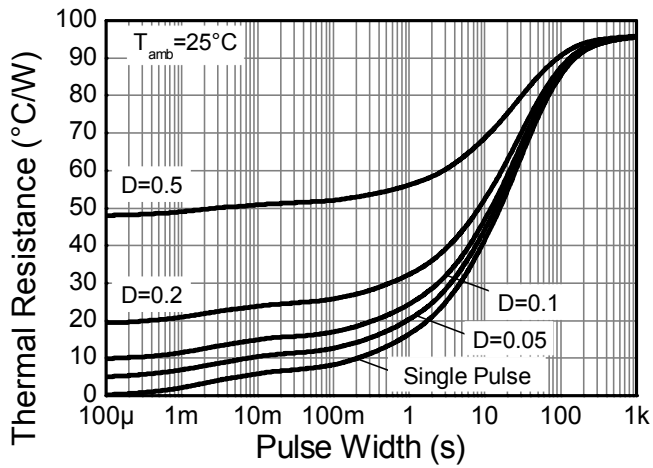
**Thermal Characteristics and Derating Information**



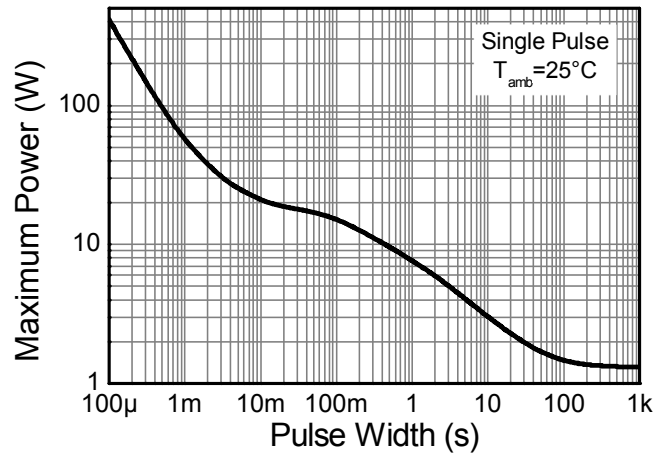
**Safe Operating Area**



**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	100	—	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 6)	$BV_{CEO}$	80	—	—	V	$I_C = 10\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	7	—	—	V	$I_E = 100\mu\text{A}$
Collector Cut-off Current	$I_{CBO}$	—	—	0.1 20	$\mu\text{A}$	$V_{CB} = 80\text{V}$ $V_{CB} = 80\text{V}, T_A = +150^\circ\text{C}$
Emitter Cut-off Current	$I_{EBO}$	—	—	20	nA	$V_{EB} = 6\text{V}$
Static Forward Current Transfer Ratio (Note 6)	$h_{FE}$	25 100 25	— — —	— 250 —		$I_C = 5\text{mA}, V_{CE} = 2\text{V}$ $I_C = 150\text{mA}, V_{CE} = 2\text{V}$ $I_C = 500\text{mA}, V_{CE} = 2\text{V}$
Collector-Emitter Saturation Voltage (Note 6)	$V_{CE(sat)}$	—	—	0.5	V	$I_C = 500\text{mA}, I_B = 50\text{mA}$
Base-Emitter Turn-On Voltage (Note 6)	$V_{BE(on)}$	—	—	1.0	V	$I_C = 500\text{mA}, V_{CE} = 2\text{V}$
Transition Frequency	$f_T$	150	—	—	MHz	$I_C = 50\text{mA}, V_{CE} = 10\text{V}$ $f = 100\text{MHz}$
Output Capacitance	$C_{obo}$	—	—	25	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Delay Time	$t_d$	—	21	—	ns	$I_C = 400\text{mA}, V_{CC} = 40\text{V},$ $I_{B1} = 20\text{mA}, I_{B2} = -20\text{mA}$
Rise Time	$t_r$	—	33	—		
Storage Time with Resistive Load	$t_s$	—	708	—		
Fall Time with Resistive Load	$t_f$	—	95	—		

Notes: 6. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

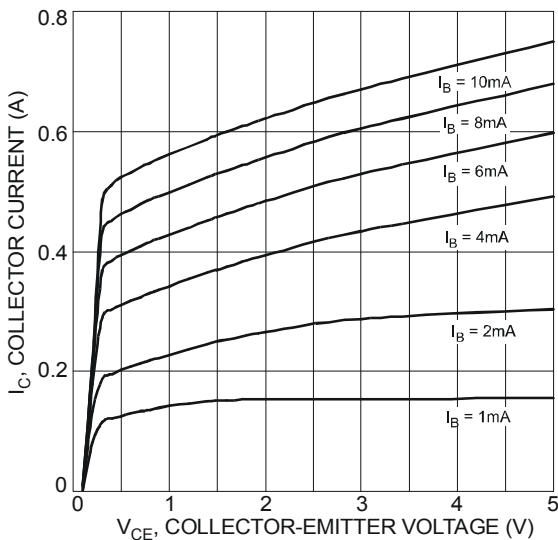


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

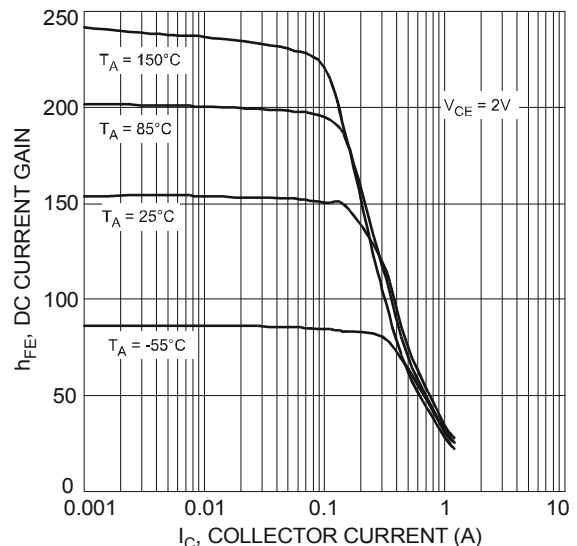


Fig. 2 Typical DC Current Gain vs. Collector Current

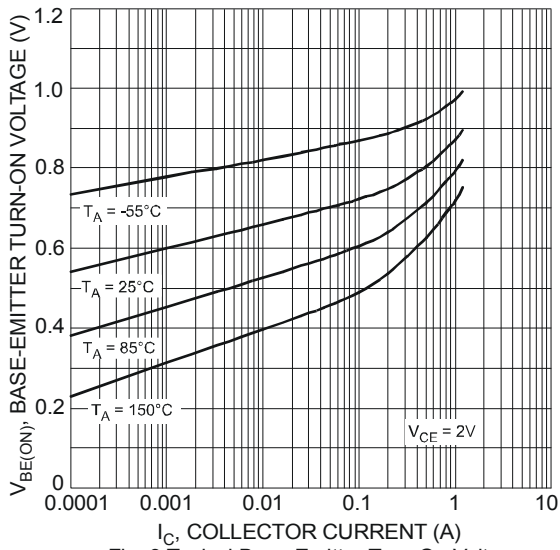


Fig. 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

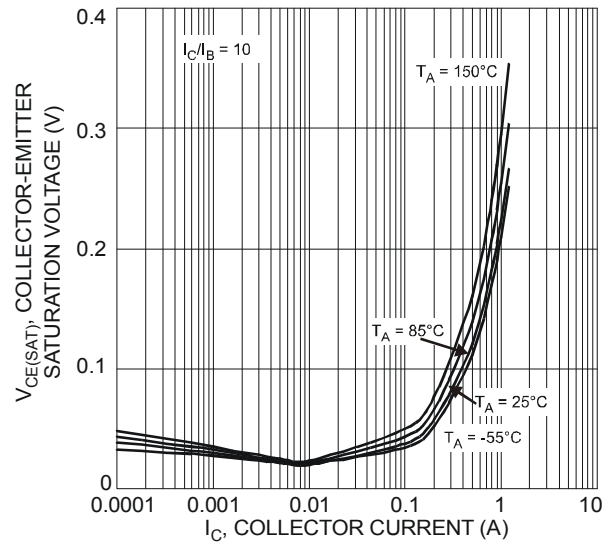


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

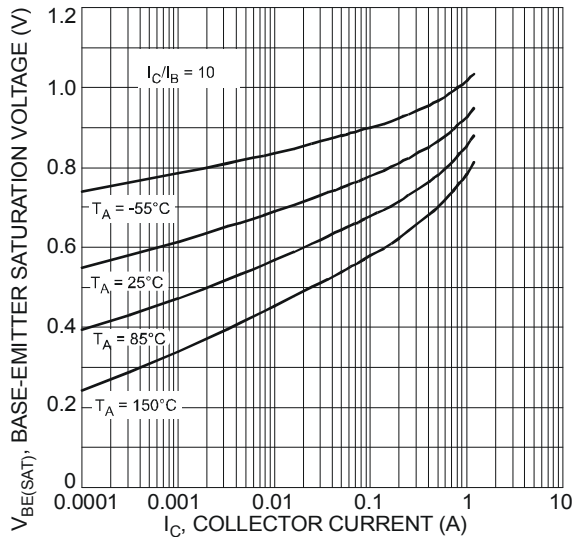


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

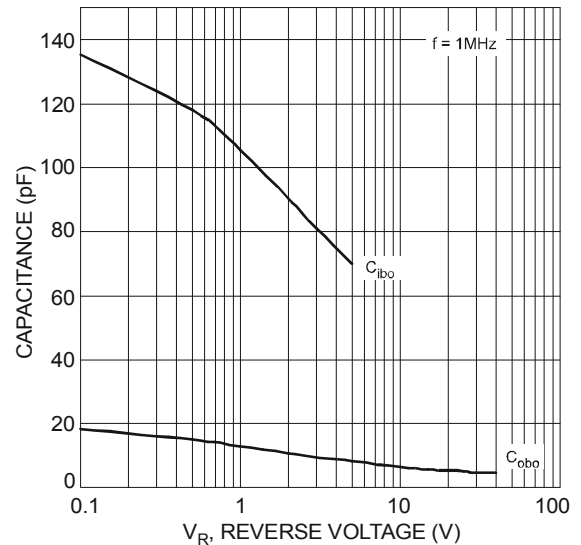


Fig. 6 Typical Capacitance Characteristics

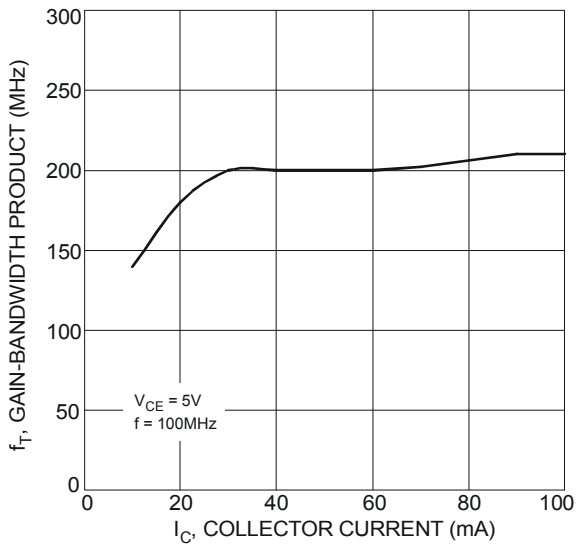
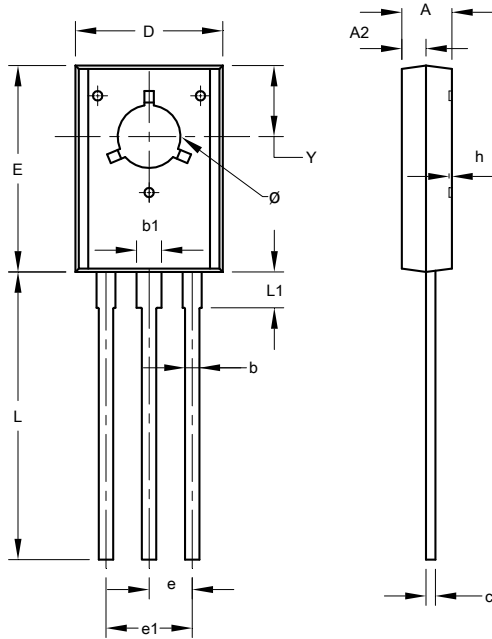


Fig. 7 Typical Gain-Bandwidth Product vs. Collector Current

## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



TO126			
Dim	Min	Max	Typ
A	2.400	2.900	-
A2	1.060	1.500	-
b	0.660	0.860	-
b1	1.170	1.470	-
c	0.400	0.600	-
D	7.400	8.200	-
E	10.60	11.20	-
e	-	-	2.280
e1	-	-	4.560
h	0.00	0.30	-
L	14.50	15.90	-
L1	1.700	2.100	-
Y	3.600	3.900	-
$\phi$	3.100	3.550	-
All Dimensions in mm			

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